

## Product Summary

<b>BV<sub>DSS</sub></b>	<b>R<sub>DS(ON)</sub> Max</b>	<b>I<sub>D</sub> Max T<sub>C</sub> = +25°C (Note 9)</b>
100V	4.3mΩ @ V <sub>GS</sub> = 10V	100A

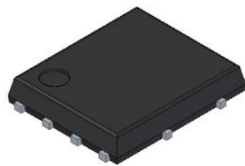
## Description

This new generation N-Channel Enhancement Mode MOSFET is designed to minimize R<sub>DS(ON)</sub>, yet maintain superior switching performance. This device is ideal for use in notebook battery power management and load switch.

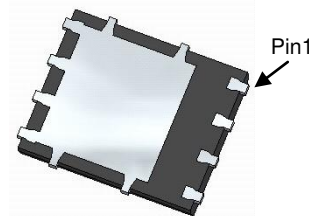
## Applications

- Motor Control
- DC-DC Converters
- Power Management

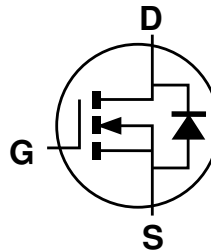
PowerDI5060-8 (Standard)



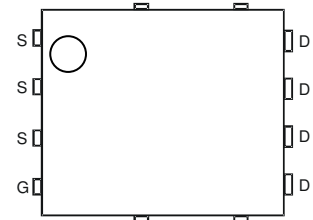
Top View



Bottom View



Internal Schematic


 Top View  
Pin Configuration

## Features

- 100% Unclamped Inductive Switching (UIS) Test in Production – Ensures More Reliable and Robust End Application
- High Conversion Efficiency
- Low R<sub>DS(ON)</sub> – Minimizes On-State Losses
- Low Input Capacitance
- Fast Switching Speed
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

## Mechanical Data

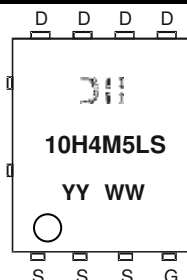
- Case: PowerDI<sup>®</sup>5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.097 grams (Approximate)

## Ordering Information (Note 4)

Part Number	Case	Packaging
DMT10H4M5LPS-13	PowerDI5060-8 (Standard)	2,500/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
  2. See [http://www.diodes.com/quality/lead\\_free/](http://www.diodes.com/quality/lead_free/) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information



- ⌐⌐⌐ = Manufacturer's Marking
- 10H4M5LS = Product Type Marking Code
- YYWW = Date Code Marking
- YY or YY = Last Two Digits of Year (ex: 19 = 2019)
- WW or WW = Week Code (01 to 53)

**Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		$V_{DSS}$	100	V
Gate-Source Voltage		$V_{GSS}$	$\pm 20$	V
Continuous Drain Current, $V_{GS} = 10\text{V}$ (Note 5)	Steady State	$T_A = +25^\circ\text{C}$	19	A
		$T_A = +70^\circ\text{C}$	15	
Continuous Drain Current, $V_{GS} = 10\text{V}$ (Note 6)	Steady State	$T_C = +25^\circ\text{C}$	100	A
		$T_C = +70^\circ\text{C}$ (Note 9)	100	
Pulsed Drain Current (10 $\mu\text{s}$ Pulse, $T_C = +25^\circ\text{C}$ , Package Limited)		$I_{DM}$	400	A
Maximum Continuous Body Diode Forward Current (Note 6)		$I_S$	100	A
Pulsed Body Diode Forward Current (10 $\mu\text{s}$ Pulse, $T_C = +25^\circ\text{C}$ , Package Limited)		$I_{SM}$	400	A
Avalanche Current (Note 7) $L = 0.3\text{mH}$		$I_{AS}$	40	A
Avalanche Energy (Note 7) $L = 0.3\text{mH}$		$E_{AS}$	240	mJ

**Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	$T_A = +25^\circ\text{C}$	$P_D$	2.3	W
Thermal Resistance, Junction to Ambient (Note 5)		$R_{\theta JA}$	54	$^\circ\text{C/W}$
Total Power Dissipation (Note 6)	$T_C = +25^\circ\text{C}$	$P_D$	113	W
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	1.1	$^\circ\text{C/W}$
Operating and Storage Temperature Range		$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b> (Note 7)						
Drain-Source Breakdown Voltage	$BV_{DSS}$	100	—	—	V	$V_{GS} = 0\text{V}, I_D = 10\text{mA}$
Zero Gate Voltage Drain Current	$I_{DSS}$	—	—	1	$\mu\text{A}$	$V_{DS} = 80\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	$I_{GSS}$	—	—	$\pm 100$	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
<b>ON CHARACTERISTICS</b> (Note 7)						
Gate Threshold Voltage	$V_{GS(TH)}$	1.3	—	2.5	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	3.5	4.3	m $\Omega$	$V_{GS} = 10\text{V}, I_D = 30\text{A}$
		—	4.7	6.2		$V_{GS} = 4.5\text{V}, I_D = 20\text{A}$
Diode Forward Voltage	$V_{SD}$	—	—	1.2	V	$V_{GS} = 0\text{V}, I_S = 30\text{A}$
<b>DYNAMIC CHARACTERISTICS</b> (Note 8)						
Input Capacitance	$C_{iss}$	—	4843	—	pF	$V_{DS} = 50\text{V}, V_{GS} = 0\text{V}$ $f = 1\text{MHz}$
Output Capacitance	$C_{oss}$	—	1302	—		
Reverse Transfer Capacitance	$C_{rss}$	—	25.5	—		
Gate Resistance	$R_g$	—	2.1	—	$\Omega$	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Total Gate Charge	$Q_g$	—	80	—	nC	$V_{DD} = 50\text{V}, I_D = 30\text{A},$ $V_{GS} = 10\text{V}$
Gate-Source Charge	$Q_{gs}$	—	14	—		
Gate-Drain Charge	$Q_{gd}$	—	18	—		
Turn-On Delay Time	$t_{D(ON)}$	—	9	—	ns	$V_{DD} = 50\text{V}, V_{GS} = 10\text{V},$ $I_D = 30\text{A}, R_g = 4.7\Omega, R_L = 1.1\Omega$
Turn-On Rise Time	$t_r$	—	26	—		
Turn-Off Delay Time	$t_{D(OFF)}$	—	76	—		
Turn-Off Fall Time	$t_f$	—	50	—		
Reverse Recovery Time	$t_{RR}$	—	63	—	ns	$I_F = 22.5\text{A}, di/dt = 100\text{A}/\mu\text{s}$
Reverse Recovery Charge	$Q_{RR}$	—	133	—	nC	

- Notes:
- Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
  - Thermal resistance from junction to soldering point (on the exposed drain pad).
  - Short duration pulse test used to minimize self-heating effect.
  - Guaranteed by design. Not subject to product testing.
  - Package limited.

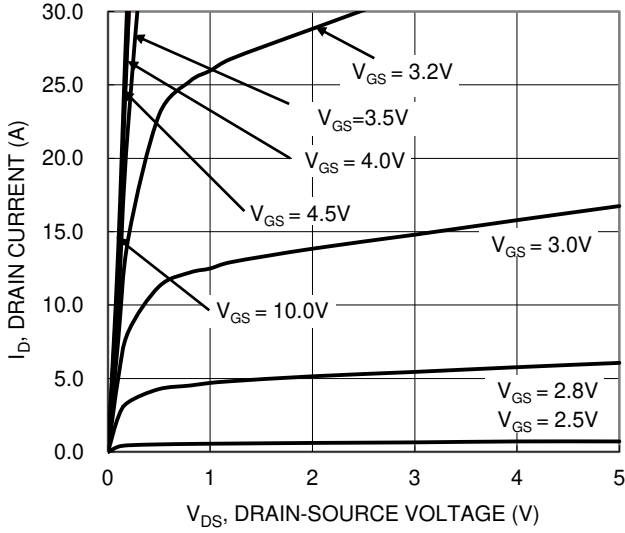


Figure 1. Typical Output Characteristic

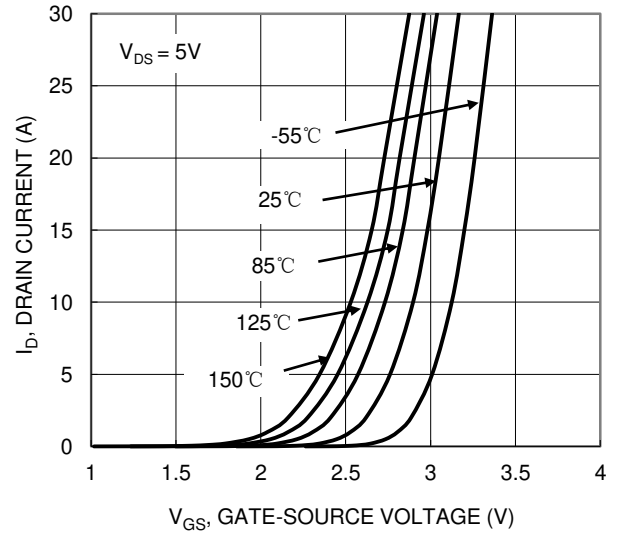


Figure 2. Typical Transfer Characteristic

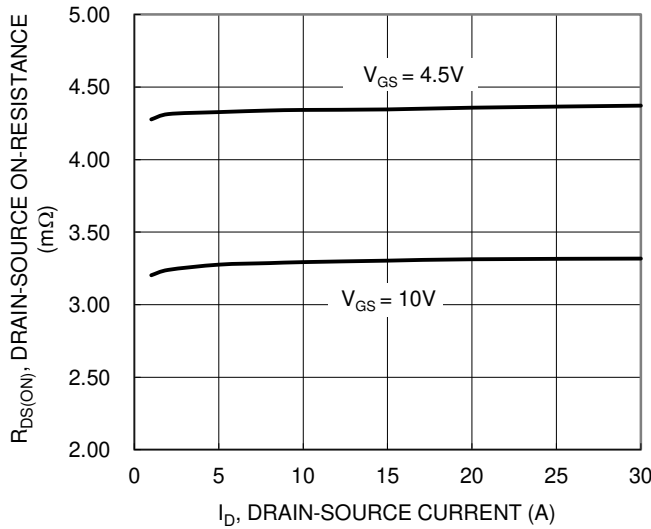


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

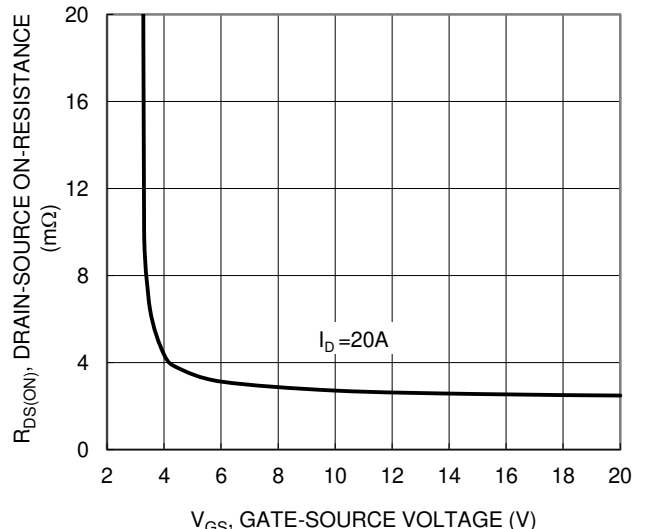


Figure 4. Typical Transfer Characteristic

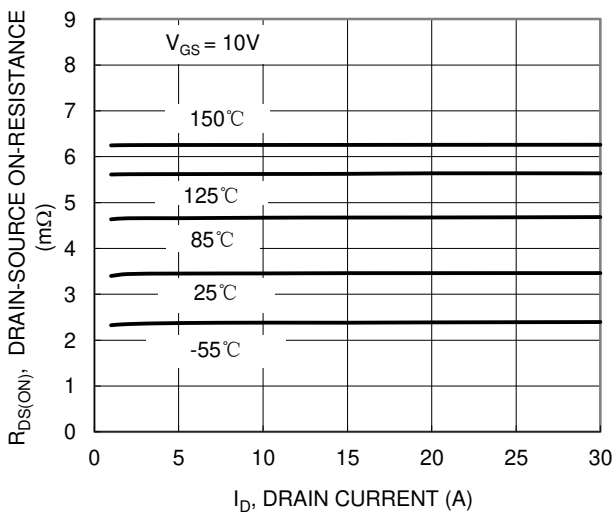


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

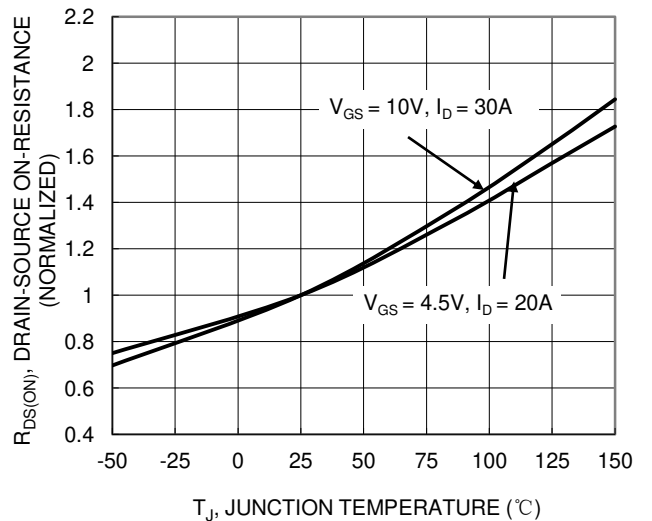


Figure 6. On-Resistance Variation with Temperature

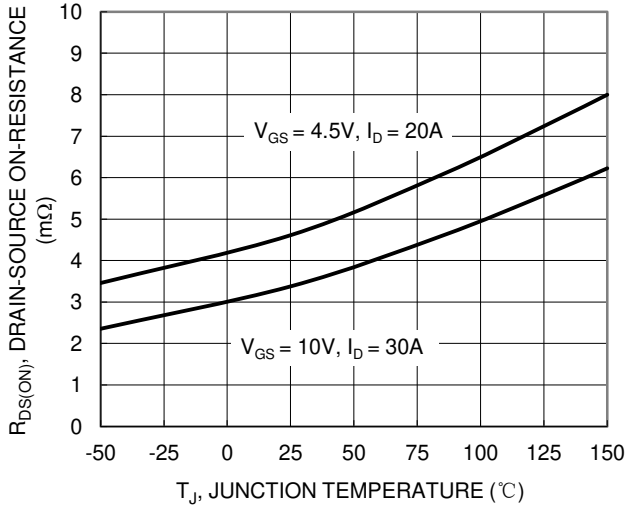


Figure 7. On-Resistance Variation with Temperature

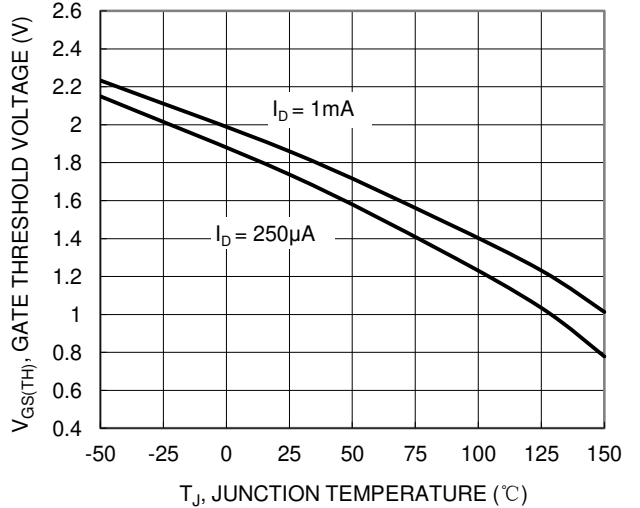


Figure 8. Gate Threshold Variation vs. Junction Temperature

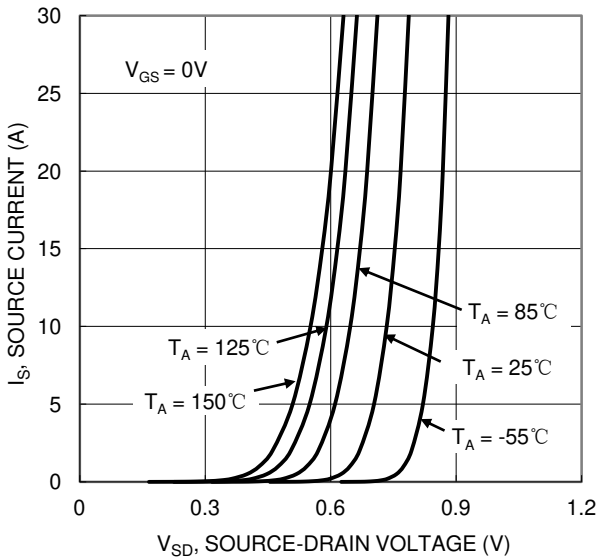


Figure 9. Diode Forward Voltage vs. Current

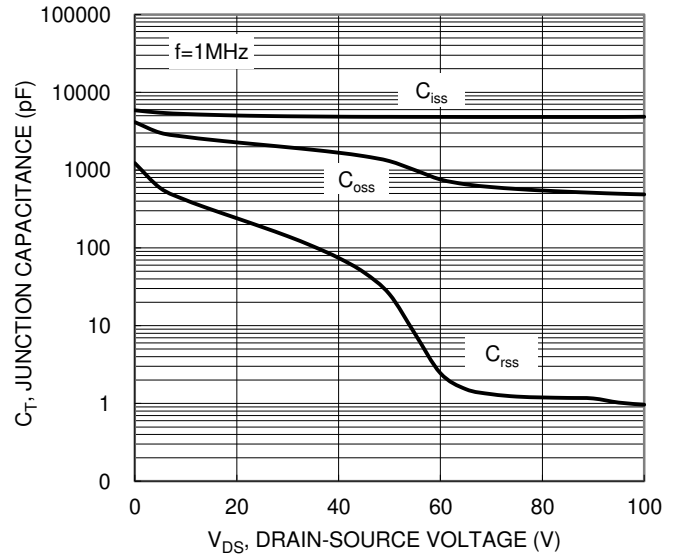


Figure 10. Typical Junction Capacitance

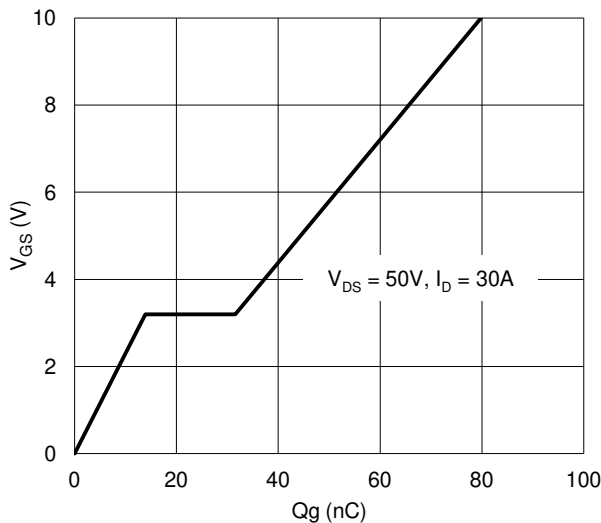


Figure 11. Gate Charge

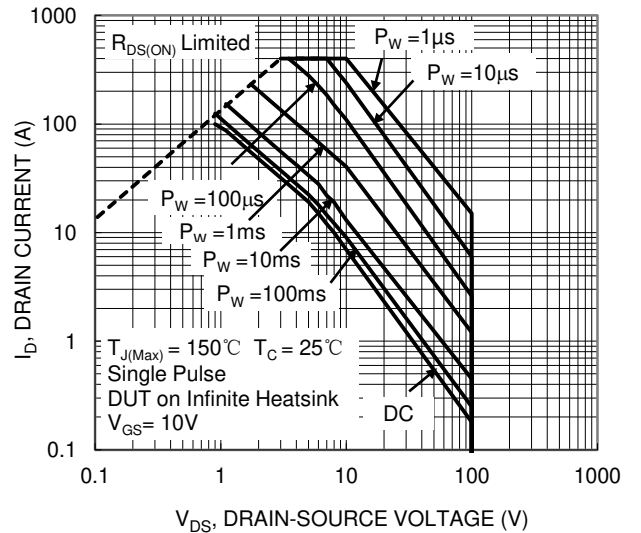


Figure 12. SOA, Safe Operation Area

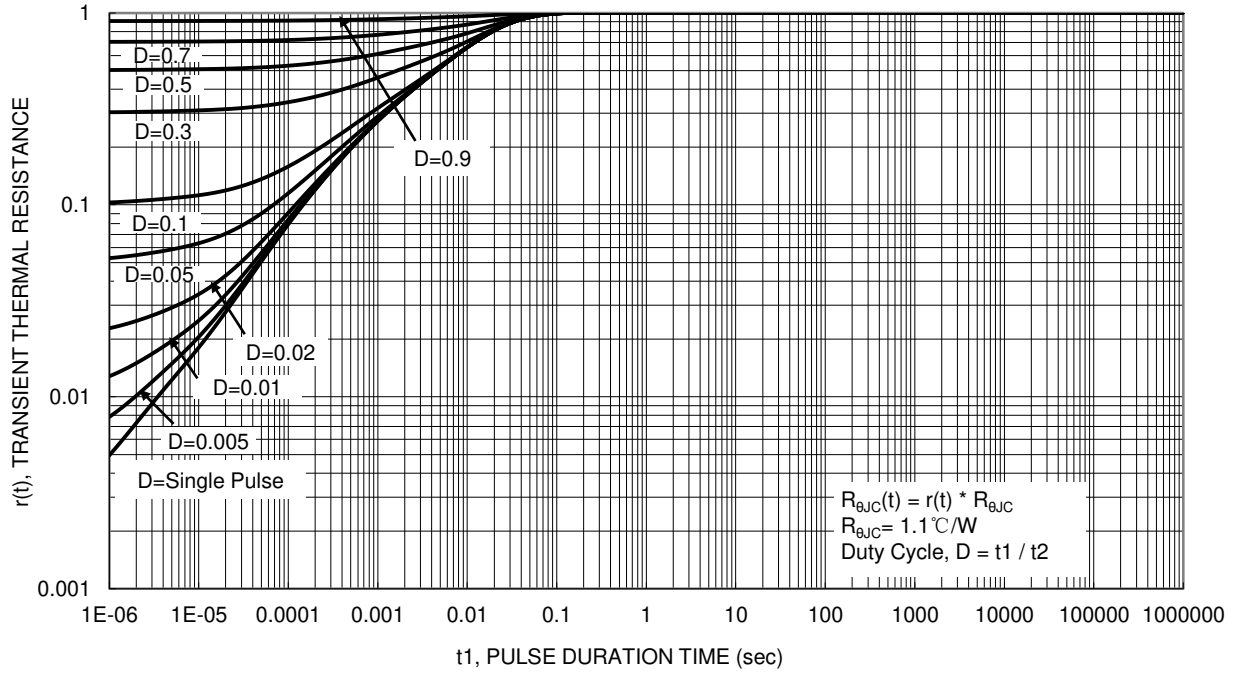
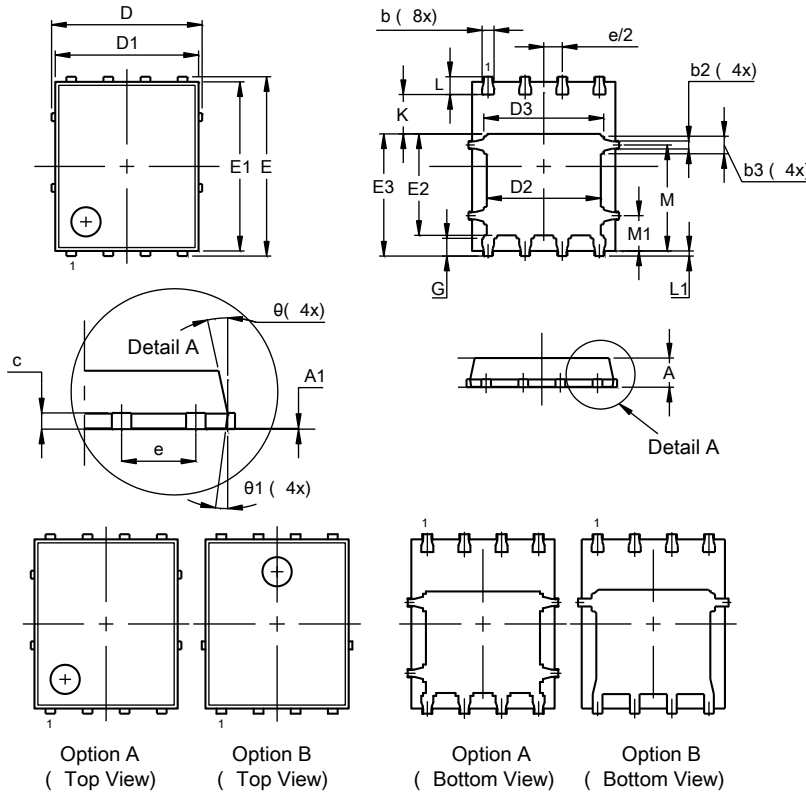


Figure 13. Transient Thermal Resistance

**Package Outline Dimensions**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**PowerDI5060-8 (Standard)**

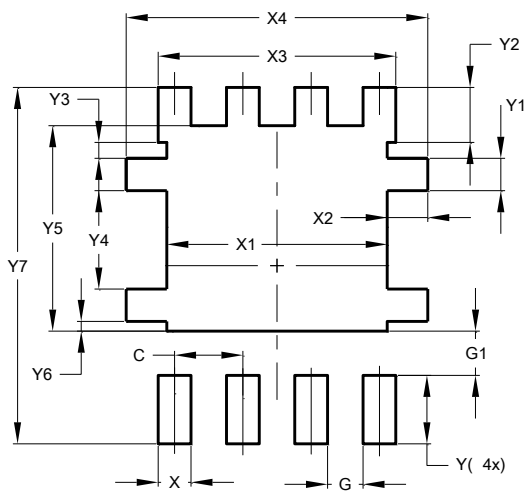


PowerDI5060-8 (Standard)			
Dim	Min	Max	Typ
A	0.90	1.20	--
A1	0.00	0.05	--
b	0.33	0.51	--
b2	0.200	0.350	--
b3	0.40	0.80	0.60
c	0.230	0.354	--
D (Option A)	5.15 BSC		
D (Option B)	5.30 BSC		
D1	4.70	5.40	--
D2	3.70	4.25	--
D3	3.90	4.70	--
E	6.15 BSC		
E1	5.60	6.06	--
E2	3.28	3.92	--
E3	3.99	4.39	--
e	1.27 BSC		
G	0.40	0.71	--
K	0.51	1.45	--
L	0.38	0.71	--
L1	0.100	0.200	--
M	3.235	4.035	--
M1	1.00	1.40	1.21
theta	8°	12°	--
theta1	6°	8°	7°
<b>All Dimensions in mm</b>			

**Suggested Pad Layout**

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

**PowerDI5060-8 (Standard)**



Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	0.610
X1	4.300
X2	0.755
X3	4.420
X4	5.610
Y	1.270
Y1	0.600
Y2	1.020
Y3	0.295
Y4	1.825
Y5	4.100
Y6	0.180
Y7	6.610

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